

**Integrated chip package structure using metal substrate and method of
manufacturing the same**

Appl. No. : 10/055,560 Confirmation No. : 6103
Applicant : Mou-Shiung Lin,
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Examiner : Mitchell, James M
Docket No. : MEGP0009USA
Customer No. : 27765

Commissioner for Patents

P.O. Box 1450
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RESPONSE TO RESTRICTION REQUIREMENT

Sir:

In response to the Restriction Requirement mailed Oct. 31, 2008, please amend the above-identified application and consider the remarks as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2

10 of this paper.

Remarks/Arguments begin on page 9 of this paper.